Various Packaging Technologies

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The Industrial Internet of Things (IIoT) or Industry 4.0 requires hyper connectivity and superintelligence in addition to performance excellence. Successfully addressing these challenges dictates the involvement of every semiconductor aspect from the design of the chip to the packaging and test portions. With its flexibility and adaptability, packaging technology will play a particularly important role in this effort. This tutorial session will provide insight into the latest advanced packaging technologies including currently highlighted high-density fan-out (HD-FO) designs.

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